

### **Proactive Yield Management using Frequent Pattern Database**

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#### Proactive Yield Management using Frequent Pattern Database



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#### Overview



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### **Motivation**





"Analyzing yield loss from both defect and wafer probe data led to the conclusion that solving systematic spatial pattern challenges in production is the missing link between inline tool control and yield improvement!"





### Technology – Build Frequent Pattern Database

Process Optimization



Yield limiting pattern on a wafer is a sign of a systematic issue due to process or tool marginalities!

Rank	Failure Type	Wafer Map	# of Wafers	Failure Rate	Route/Stage : Step	Process Tool
1	Edge Arc	$\bigcirc$	410	0.32	C-MET1ET : CE51B	CELRC01X
2	SP2		350	0.28	C-BCAPCLN: CA085	CAFSI02X
3	Center Core		100	0.10	C-YWDEP2 : CY311	CY310



**Benefits** 



#### Inline Monitoring & Lot/Wafer Disposition Strategy



#### Learning from UNKNOWN



#### **Drive actions in production (OCAP)**

- Lot Hold, Tool Downs, Rework, Chamber Actions and Test wafer measurements
- Interacting with SPC



#### Yield & Productivity Improvement

- Timely Root Cause
- Dashboards for High Impacting Route Step & Tools

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#### **Quality Improvement**

- Proactive Die Binning
- Pattern Search
- Event Scope





Introduction / Methodology

Six months of AOI & Wafer Probe production data was used.







### **Discover Patterns Operational Workflow**







# Learning from the "UNKNOWN"

• An UNKNOWN pattern is an identified spatial signature that does not match an existing pattern in the production database



- Understand top-n high impacting new patterns that start to emerge & go unnoticed
- Efficiently maintain comprehensive Pattern Library
- Proactive response to production issues

Pattern Pareto based on hundreds of feature vectors





### Results of learning from the "UNKNOWN" Patterns



# Pattern Pareto based on hundreds of feature vectors from UNKNOWN Patterns over 3 months

# SEAGATE

#### UNKNOWN Patterns tracked weekly

- Three key patterns were discovered: System Scratch, Small Cluster, and Ring Light.
- Analysis shows the potential for hundreds of wafers to be classified and correlated to yield limiting spatial issues.



### Challenges with Scratch Detection



Additional post processing algorithm is dedicated to running image-based scratch detection instead of defect-based detection using dynamic threshold determination (based on density and distribution) to eliminate or reduce false positives.





### Case Study #1: Pattern Search Technique Improves Quality

- Contributes to proactive analysis and build the Frequent Pattern Database
- Defect edge band pattern was used as reference to pull top 50 similar wafer probe patterns
- This powerful tool explicitly defines inline to EOL pattern commonalities and can be used to obtain accurate kill ratios







# Case Study #2: SPR Identifies Root Cause Tool in CMP Excursion

Yield excursion linked to a recurring scratch formation in the CMP process.

**Production limitations & low defect density** impacts quality & contributes to scrap





Amps

Motor Amps

Slurry Dispense

and Arm Force

Wet Idle Time **DI Water Flow** 

Spindle Head Speed,

Wafer Chuck Placement/Retry

Processing time (by platen)





Integration of this signature into the Frequent Pattern Database quickly highlights the root cause tool and event timeline.



### Case Study #3: Killer Pattern Excursions by Process Tool & Date

- Chemical dispersion challenges at a strip step cause semi-circular ring like pattern
- Application of real-time alarm monitoring will notify the engineer and maintenance staff of this yield-impacting defect pattern, allowing for quick reaction times
- This known failure mode requires timely detection so wafer can be reworked to avoid scrap



Trend split by Tool & Pattern, helps to find signal which would have been missed otherwise

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# **Yield Improvement / Line Control**

#### Yield Optimizer

In-process tool data

Inline Metrology/output data

**Frequent Patterns** 

 Analyze the relationships between in-process data and End-of-Line test or output results

> Neural **Network(s)**

> > Performance

 Recommend changes to the in-process targets to optimize the yield/output parameters





### Improve Production Efficiency – React Faster & Reduce Scrap

#### **Monitoring Dashboards**

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			1 1	4.76	3	14.29	6	28.57	5	23.81	2	9.52	5	23.81	0	0	2	9.52	3	14.29	15	71.43
			2 1	5.56	3	16.67	3	16.67	2	11.11	5	27.78	5	27.78	1	5.56	4	22.22	6	33.33	14	77.78
			1 1	6.25	0	0	6	37.5	5	31.25	1	6.25	5	31.25	0	0	1	6.25	2	12.5	11	68.75
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			5 0	0	0	0	3	60	4	80	0	0	1	20	0	0	0	0	1	20	5	100
			3 0	0	3	42.86	0	0	0	0	1	14.29	0	0	0	0	1	14.29	1	14.29	4	57.14
			2 (	0	3	42.86	0	0	0	0	1	14.29	0	0	0	0	1	14.29	1	14.29	4	57.14
			1 0	0	3	42.86	0	0	0	0	1	14.29	0	0	0	0	1	14.29	1	14.29	4	57.14
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#### Daily Pass Down Report to production highlights process tools that contribute to yield limiting alarm conditions

Engineering productivity improves ~25% by linking Pattern based Equipment Study with AOI data





### **Conclusions & Future Work**

#### **AI based Frequent Patterns Implementation**

- Good: Key application
  - -Shutdown faulty tools
  - -Outline excursion scope
- Better: Reactive Analysis
  - Expedient association of wafer spatial signatures to process step & tool
- Best: Proactive Yield Management
  - -Build Frequent Pattern Database
  - Avenue for proactive process control, yield enhancement & fab productivity

#### **Continuous Improvement**

- Discover Patterns on Metrology Data
- Whole wafer image-based Pattern Classification
- Frequent Patterns input to Yield Optimizer for Process Optimization





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# **Thank You**

谢谢   <b>謝謝</b>	ありがとう	Obrigado
Danke	감사합니다	Merci

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